K&S-101US1

Appln. No.: 10/786,188

Amendment Dated May 31, 2005

Reply to Office Action of February 17, 2005

<u>Amendments to the Claims:</u> This listing of claims will replace all prior versions, and listings, of claims in the application

Listing of Claims

- 1-16. (Cancelled)
- 17. (Original) A method of manufacturing a capillary bonding tool for bonding a fine wire to a substrate, the method comprising the steps of:

forming a cylindrical body;

forming a taper at a first end of the body;

forming an orifice extending along a longitudinal axis of the body; and coating at least a portion of the orifice with a polymer.

- 18. (Original) The method according to claim 17, wherein the coating step forms a substantially uniform continuous coating having a thickness of up to about 2.0 microns.
- 19. (Original) The method according to claim 17, wherein the coating step forms a substantially uniform continuous coating having a thickness of at least about 0.1 micron.
- 20. (Original) The method according to claim 17, wherein the coating step comprises the steps of:

forming a precursor monomer at a first temperature and a first pressure; and forming the coating from the precursor monomer at a second temperature and pressure.

21. (Original) The method according to claim 20, wherein

the first temperature is about 690°C,

the first pressure is about 0.5 torr,

the second temperature is about 25°C, and

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the second pressure is about 0.1 torr.

- 22. (Original The method according to claim 20, wherein the precursor monomer is formed from a di-Para-Xylyene dimer vaporized at about 150°C and about 1.0 torr followed by a pyrolesis at about 690°C and about 0.5 torr.
- 23. (Original) The method according to claim 17, wherein the capillary is formed by i) one of direct ceramic dye pressing and ii) injection molding, and machined to a final shape by one of i) grinding and ii) Electro discharge machining.
- 24. (Withdrawn) A bonding tool for bonding a wire to a substrate, comprising: a body portion;
 - a working tip coupled to one end of the body;
 - a first coating disposed over at least a portion of a surface of the orifice; and

an orifice extending along a longitudinal axis of the body and the working tip;

- a second coating disposed over at least a portion of an exterior surface of the body.
- 25. (Withdrawn) A capillary bonding tool according to claim 24, wherein the first coating is a polymer and the second coating is other than a polymer.
- 26. (Withdrawn) A capillary bonding tool according to claim 25, wherein the second coating is one of an alumina and Si_3N_4 .
- 27. (Original) A method of manufacturing a capillary bonding tool for bonding a fine wire to a substrate, the method comprising the steps of:

forming an orifice extending along a longitudinal axis of the bonding tool;

coating at least a portion of the orifice with a polymer; and

coating at least a portion of an exterior surface of the bonding tool with a non-polymer coating.